

## General Description

The MY75P03NE5 is the single P-Channel logic enhancement mode power field effect transistors to provide excellent RDS(on), low gate charge and low gate resistance.

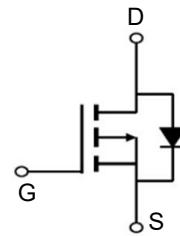
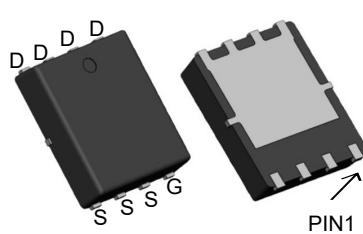


## Features

X <sub>FUU</sub>	-30	X
I <sub>G</sub>	-75	C
T <sub>FUQP+CVXI U? 10X+</sub>	5.6	o Á
T <sub>FUQP+CVXI U? 4.5X+</sub>	9.5	o Á

## Application

- Battery protection
- Load switch
- Uninterruptible power supply
- DC/DC Converter



## Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
MY75P03NE5	PDFN5*6-8L	T72DPD	5000

## Absolute Maximum Ratings (T<sub>J</sub>=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	-30	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>c</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ -10V <sup>1,6</sup>	-75	A
I <sub>D</sub> @T <sub>c</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ -10V <sup>1,6</sup>	-55	A
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	-200	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	80	mJ
I <sub>AS</sub>	Avalanche Current	-40	A
P <sub>D</sub> @T <sub>c</sub> =25°C	Total Power Dissipation <sup>4</sup>	90	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 175	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 175	°C
R <sub>θJA</sub>	Thermal Resistance Junction-ambient <sup>1</sup> (t≤ 10S)	20	°C/W
	Thermal Resistance Junction-ambient <sup>1</sup> (Steady State)	50	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-case <sup>1</sup>	1.6	°C/W

**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =-250uA	-30	---	---	V
R <sub>DSON</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =-10V , I <sub>D</sub> =-20A	---	5.6	7.2	mΩ
		V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-15A	---	9.5	12	mΩ
V <sub>GTH</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =-250uA	-1.2	---	-2.5	V
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =-24V , V <sub>GS</sub> =0V , T <sub>J</sub> =25 °C	---	---	-1	uA
		V <sub>DS</sub> =-24V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C	---	---	-5	
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V , V <sub>DS</sub> =0V	---	---	±100	nA
R <sub>G</sub>	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz	---	1.2	---	Ω
Q <sub>g</sub>	Total Gate Charge (-10V)	V <sub>DS</sub> =-15V , V <sub>GS</sub> =-10V , I <sub>D</sub> =-18A	---	60	---	nC
Q <sub>gs</sub>	Gate-Source Charge		---	9	---	
Q <sub>gd</sub>	Gate-Drain Charge		---	15	---	
T <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> =-15V , V <sub>GS</sub> =-10V , R <sub>G</sub> =3.3 , I <sub>D</sub> =-20A	---	17	---	ns
T <sub>r</sub>	Rise Time		---	40	---	
T <sub>d(off)</sub>	Turn-Off Delay Time		---	55	---	
T <sub>f</sub>	Fall Time		---	13	---	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =-25V , V <sub>GS</sub> =0V , f=1MHz	---	3450	---	pF
C <sub>oss</sub>	Output Capacitance		---	255	---	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	140	---	
I <sub>S</sub>	Continuous Source Current <sup>1,5</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current	---	---	-70	A
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =-1A , T <sub>J</sub> =25°C	---	---	-1.2	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> =-20A , di/dt=100A/μs , T <sub>J</sub> =25°C	---	22	---	nS
Q <sub>rr</sub>	Reverse Recovery Charge		---	72	---	nC

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3.The EAS data shows Max. rating . The test condition is V<sub>DD</sub>=-50V,V<sub>GS</sub>=-10V,L=0.1mH,I<sub>AS</sub>=-40A
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub> , in real applications , should be limited by total power dissipation
- 6.The maximum current rating is package limited.

### Typical Characteristics

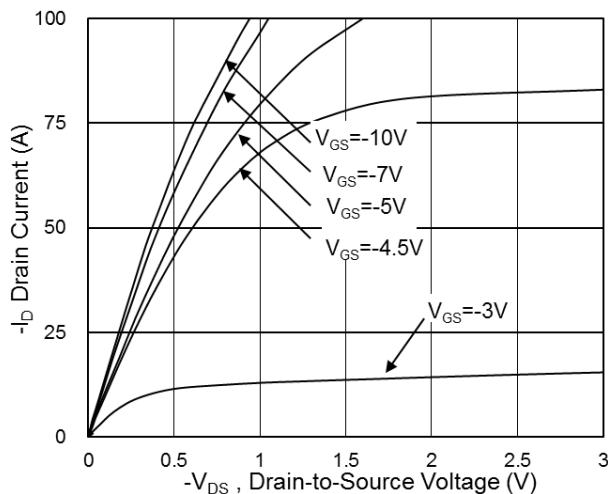


Fig.1 Typical Output Characteristics

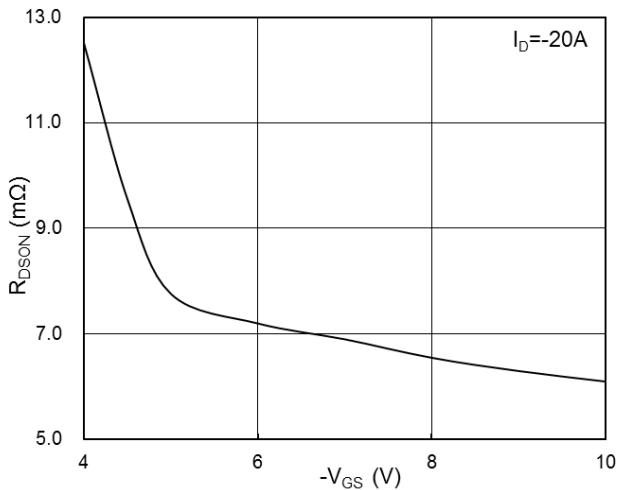


Fig.2 On-Resistance vs. Gate-Source Voltage

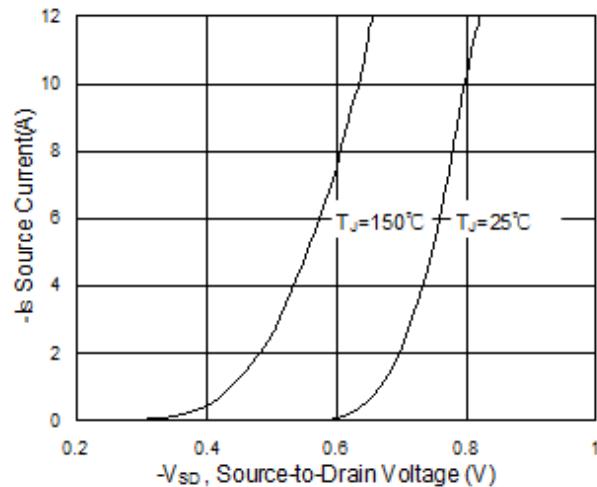


Fig.3 Forward Characteristics of Reverse

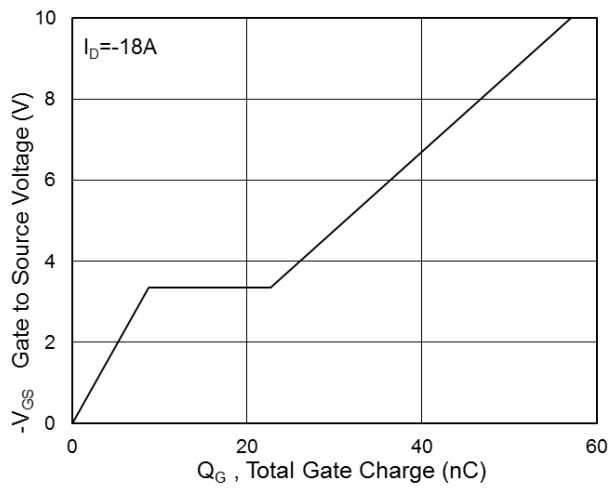
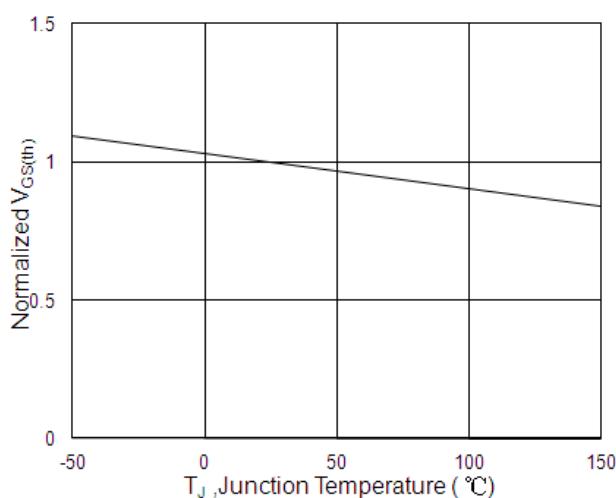
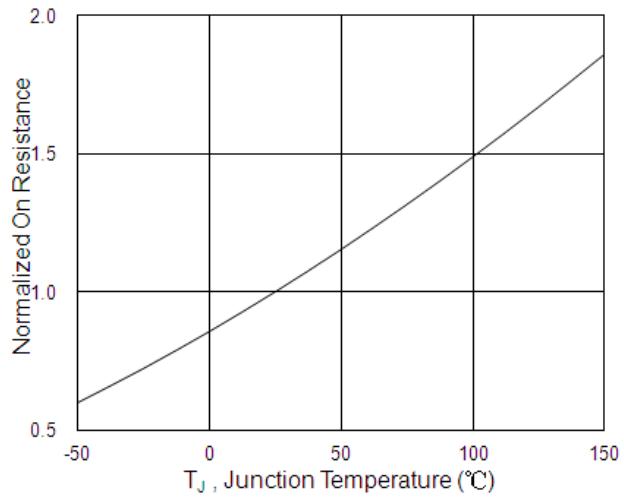


Fig.4 Gate-Charge Characteristics

Fig.5 Normalized  $-V_{GS(th)}$  vs.  $T_J$ Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$

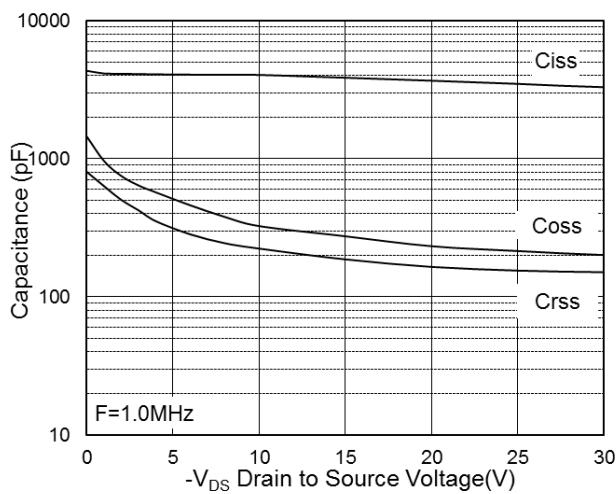


Fig.7 Capacitance

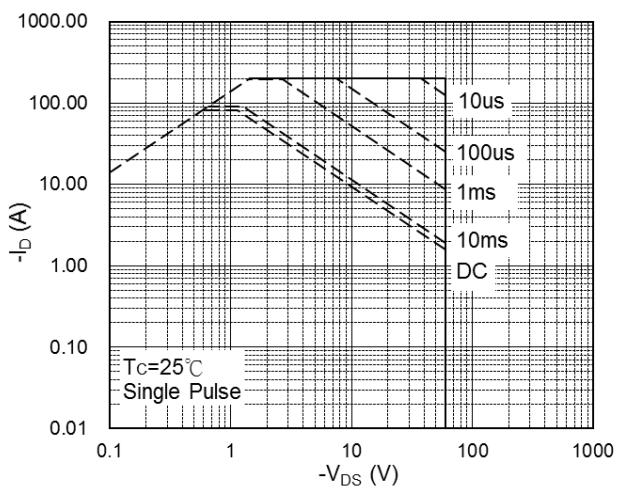


Fig.8 Safe Operating Area

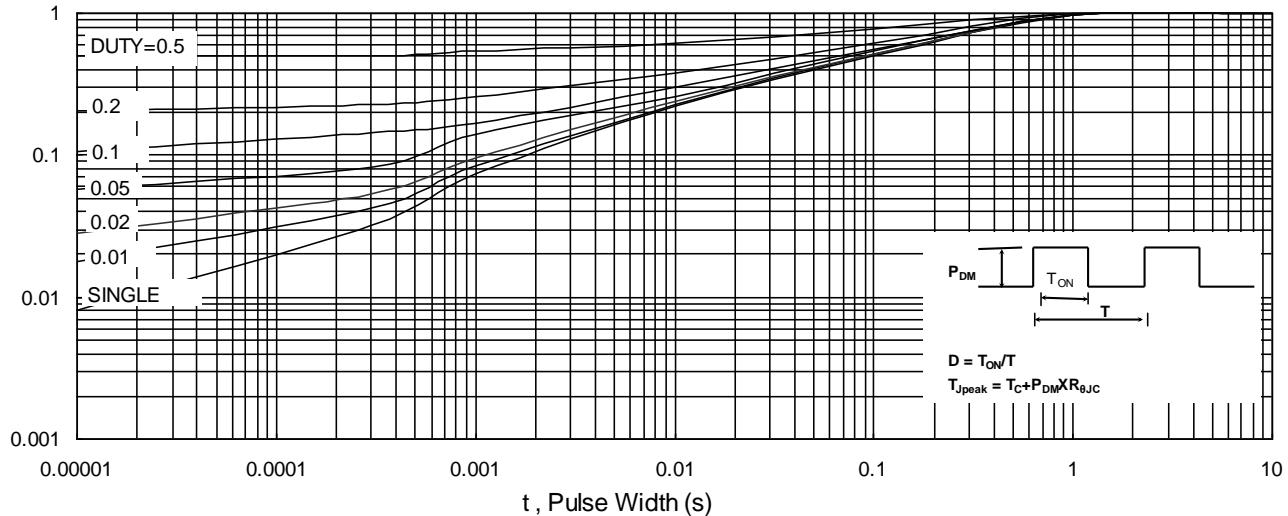


Fig.9 Normalized Maximum Transient Thermal Impedance

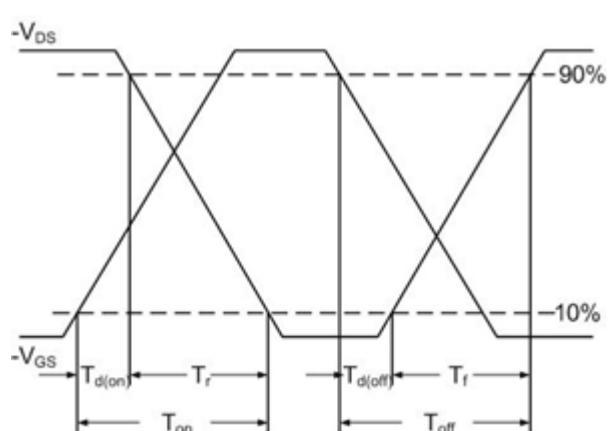


Fig.10 Switching Time Waveform

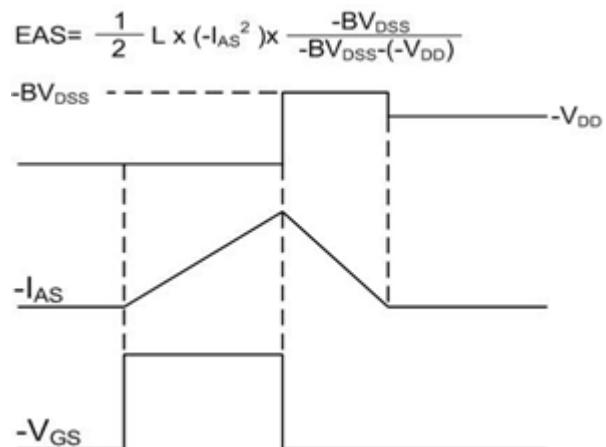
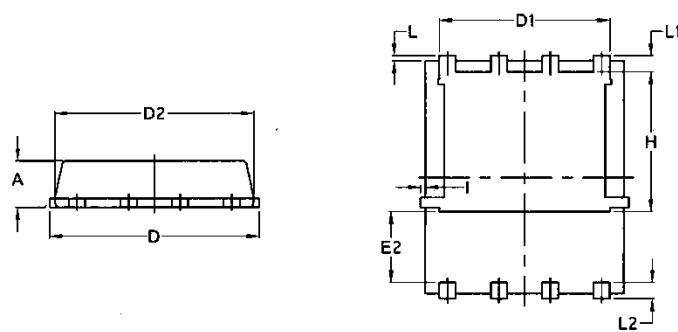
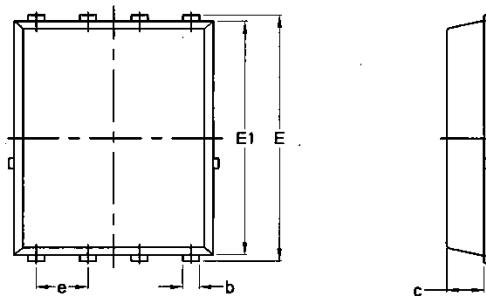


Fig.11 Unclamped Inductive Switching Waveform

**Package Mechanical Data-DFN5\*6-8L-JQ Single**


Symbol	Common			
	mm		Inch	
	Mim	Max	Min	Max
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.0970	0.0324	0.082
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
E	5.95	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.60	/	0.0630	/
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
H	3.30	3.50	0.1299	0.1378
I	/	0.18	/	0.0070